

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
Ø	10.0	PLATED	255
T20	20.0	PLATED	6
T35	35.0	PLATED	20
T42	42.0	PLATED	35
T43	43.0	PLATED	32
T60	60.0	PLATED	6
T70	170.0	PLATED	2

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:

a. FR4 PER IPC 4101B/24 /26, OR /28.

b. SIGNAL LAYERS TO BE 1 OZ. COPPER.

c. PLANE LAYERS TO BE 1 OZ. COPPER.

d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR VIOLET, BOTH SIDES.
6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

~~b. IMMERSION SILVER TAG.~~
7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH

b. HOLE DIMENSIONS APPLY AFTER PLATING.

c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".

e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

